International TOR Rectifier

IRS2011(S)PbF

Features

- Floating channel designed for bootstrap operation
- Fully operational up to +200 V
- Tolerant to negative transient voltage, dV/dt immune
- Gate drive supply range from 10 V to 20 V
- Independent low-side and high-side channels
- · Input logic HIN/LIN active high
- · Undervoltage lockout for both channels
- 3.3 V and 5 V input logic compatible
- · CMOS Schmitt-triggered inputs with pull-down
- · Matched propagation delay for both channels
- · RoHS compliant

Applications

- Audio Class D amplifiers
- · High power DC-DC SMPS converters
- DC motor drive

Description

The IRS2011 is a high power, high speed power MOSFET driver with independent high and low-side referenced output channels, ideal for Audio Class D and DC-DC converter applications. Logic inputs are compatible with standard CMOS or LSTTL output, down to 3.3 V logic. The output drivers feature a

Product Summary

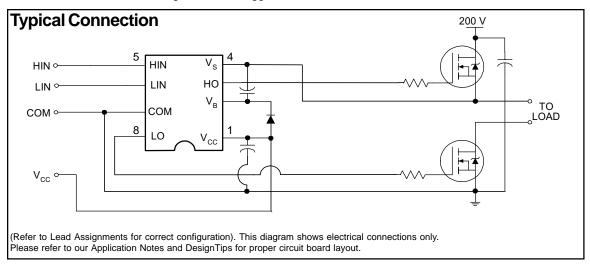
Voffset	200 V max.
I _O +/-	1.0 A /1.0 A typ.
Vout	10 V - 20 V
t _{on/off}	60 ns typ.
Delay Matching	20 ns max.
t _{on/off}	60 ns typ.

HIGH AND LOW SIDE DRIVER

Packages



high pulse current buffer stage designed for minimum driver cross-conduction. Propagation delays are matched to simplify use in high frequency applications. The floating channel can be used to drive an N-channel power MOSFET in the high-side configuration which operates up to 200 V. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction.



Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min.	Max.	Units	
VB	High-side floating supply voltage		-0.3	220 (Note 1)	
٧s	High-side floating supply offset voltage		V _B - 20	V _B + 0.3	
Vно	High-side floating output voltage		Vs - 0.3	V _B + 0.3	
Vcc	Low-side fixed supply voltage		-0.3	20 (Note 1)	V
VLO	Low-side output voltage		-0.3	V _{CC} +0.3	
V _{IN}	Logic input voltage (HIN & LIN)	-0.3	V _{CC} +0.3		
dV _s /dt	Allowable offset supply voltage transient (F	_	50	V/ns	
PD	Package power dissipation @ T _A = +25 °C	(8-lead DIP)	_	1.0	10/
rD	Fackage power dissipation @ 1A = +25 C	(8-lead SOIC)	_	0.625	W
DTI	Thermal registance innetion to embient	(8-lead DIP)	_	125	°C/W
RTH _{JA}	Thermal resistance, junction to ambient (8-lead SOIC)		_	200	C/VV
TJ	Junction temperature	_	150		
T _S	Storage temperature		-55	150	°C
TL	Lead temperature (soldering, 10 seconds)		_	300	

Note 1: All supplies are fully tested at 25 V and an internal 20 V clamp exists for each supply.

Recommended Operating Conditions

For proper operation the device should be used within the recommended conditions. The Vs and COM offset ratings are tested with all supplies biased at a 15 V differential.

Symbol	Definition	Min.	Max.	Units
V _B	High-side floating supply absolute voltage	V _S + 10	V _S + 20	
٧s	High-side floating supply offset voltage	Note 2	200	
V _{HO}	High-side floating output voltage	Vs	V _B	,, l
Vcc	Low-side fixed supply voltage	10	20	V
V _{LO}	Low-side output voltage	0	V _{cc}	
V _{IN}	Logic input voltage (HIN & LIN)	COM	5.5	
T _A	Ambient temperature	-40	125	

Note 2: Logic operational for V_S of -5 V to +200 V. Logic state held for V_S of -5 V to -V_{BS}.

Dynamic Electrical Characteristics

 V_{BIAS} (V_{CC} , V_{BS}) = 15 V, C_L = 1000 pF, T_A = 25 °C unless otherwise specified. Figure 1 shows the timing definitions.

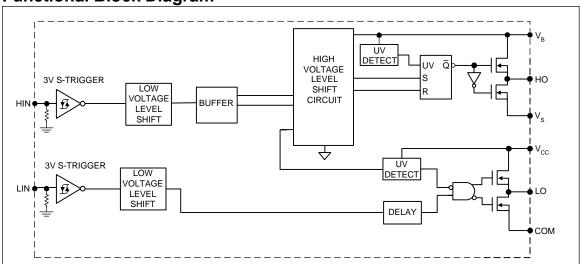
Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
ton	Turn-on propagation delay	_	60	80		Vs = 0V
t _{off}	Turn-off propagation delay	_	60	80		V _S = 200V
t _r	Turn-on rise time	_	25	40		
tf	Turn-off fall time	_	15	35	ns	
DM1	Turn-on delay matching ton (H) - ton (L)	_	_	20		
DM2	Turn-off delay matching t _{off} (H) - t _{off} (L)	_	_	20		-

Static Electrical Characteristics

 V_{BIAS} (V_{CC} , V_{BS}) = 15 V, and T_A = 25 °C unless otherwise specified. The V_{IN} , V_{TH} , and I_{IN} parameters are referenced to COM and are applicable to all logic input leads: HIN and LIN. The V_O and I_O parameters are referenced to COM and are applicable to the respective output leads: HO or LO.

Symbol	Definition	Min.	Тур.	Max.	Units	Test Conditions
V _{IH}	Logic "1" input voltage	2.5	_	_		V _{CC} = 10 V - 20 V
V _{IL}	Logic "0" input voltage	_	_	0.7	V	VCC = 10 V - 20 V
V _{OH}	High level output voltage, V _{BIAS} - V _O	_	_	1.4		I _O = 0 A
V _{OL}	Low level output voltage, VO	_	_	0.1		I _O = 20 mA
ILK	Offset supply leakage current	_	_	50		V _B =V _S = 200 V
I _{QBS}	Quiescent V _{BS} supply current	_	120	210		V _{IN} = 0 V or 3.3 V
IQCC	Quiescent V _{CC} supply current	_	200	300	μA	VIN = 0 V 01 3.3 V
I _{IN+}	Logic "1" input bias current	_	3	10		V _{IN} = 3.3 V
I _{IN-}	Logic "0" input bias current	_	_	5.0		V _{IN} = 0 V
V _{BSUV+}	V _{BS} supply undervoltage positive going threshold	8.3	9.0	9.7		
V _{BSUV} -	V _{BS} supply undervoltage negative going threshold	7.5	8.2	8.9	V	
V _{CCUV+}	V _{CC} supply undervoltage positive going threshold	8.3	9.0	9.7		
V _{CCUV} -	V _{CC} supply undervoltage negative going threshold	7.5	8.2	8.9		
lO+	Output high short circuit pulsed current	_	1.0	_	_	V _O = 0 V, PW = 10 μs
l _{O-}	Output low short circuit pulsed current		1.0	_	A	V _O = 15 V, PW = 10 μs

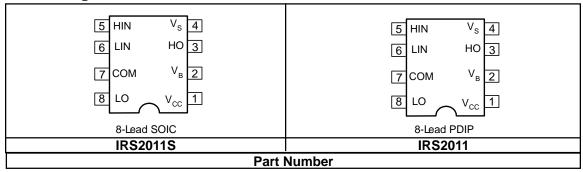




Lead Definitions

Symbol	Description
HIN	Logic input for high-side gate driver output (HO), in phase
LIN	Logic input for low-side gate driver output (LO), in phase
VB	High-side floating supply
НО	High-side gate drive output
Vs	High-side floating supply return
Vcc	Low-side supply
LO	Low-side gate drive output
COM	Low-side return

Lead Assignments



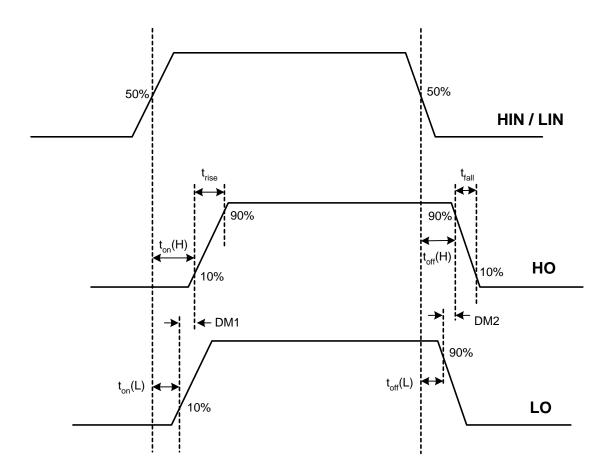


Figure 1. Timing Diagram

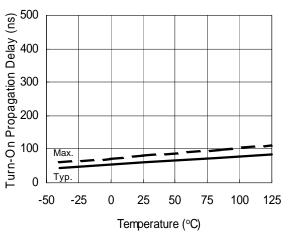


Figure 2A. Turn-On Propagation Delay vs. Temperature

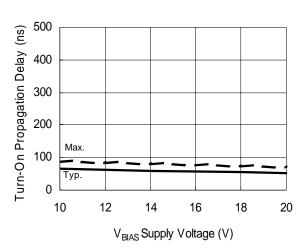


Figure 2B. Turn-On Propagation Delay vs. Supply Voltage

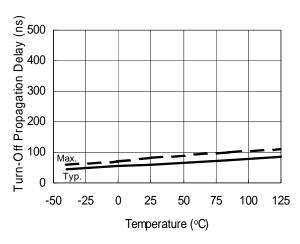


Figure 3A. Turn-Off Propagation Delay vs. Temperature

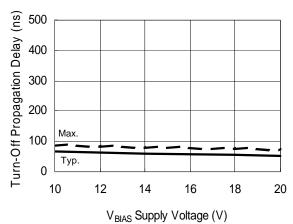
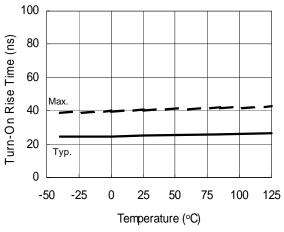


Figure 3B. Turn-Off Propagation Delay vs. Supply Voltage



Fiure 4A. Turn-On Rise Time vs.Temperature

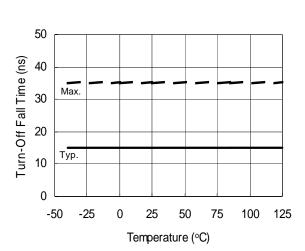


Figure 5A. Turn-Off Fall Time vs. Temperature

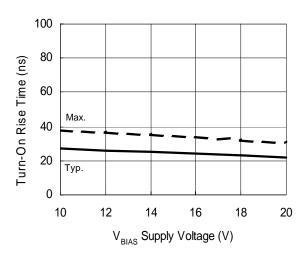


Figure 4B. Turn-On Rise Time vs. Supply Voltage

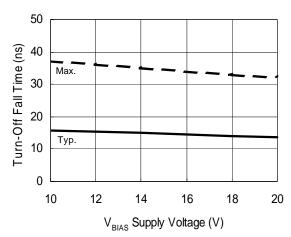
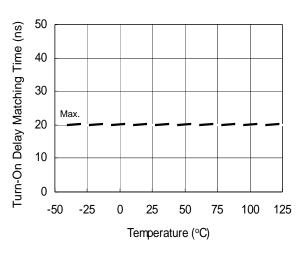


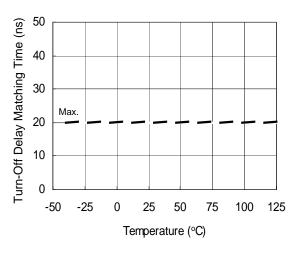
Figure 5B. Turn-Off Fall Time vs. Supply Voltage



50 Turn-On Delay Matching Time (ns) 40 30 Max. 20 10 0 -25 0 50 75 -50 25 100 125 V_{CC} Supply Voltage (V)

Figure 6A. Turn-On Delay Matching Time vs. Temperature

Figure 6B. Turn-On Delay Matching Time vs. Supply Voltage



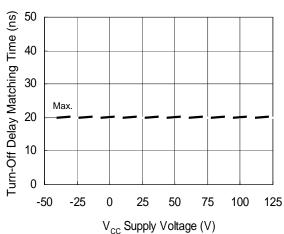


Figure 7A. Turn-Off Delay Matching Time vs. Temperature

Figure 7B. Turn-Off Delay Matching Time vs. Supply Voltage

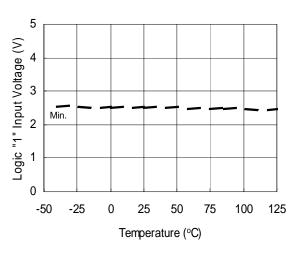
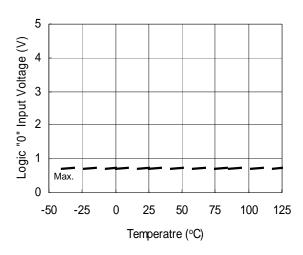


Figure 8A. Logic "1" Input Voltage vs. Temperature

Figure 8B. Logic "1" Input Voltage vs. Supply Voltage



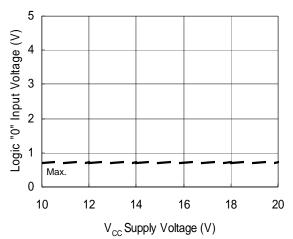
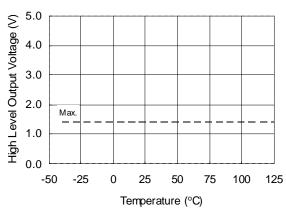


Figure 9A. Logic "0" Input Voltage vs. Temperature

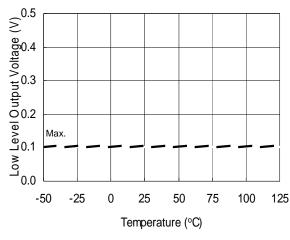
Figure 9B. Logic "0" Input Voltage vs. Supply Voltage



5.0 9bg 4.0 1.0 10 12 14 16 18 20 V_{BAIS} Supply Voltage (V)

Figure 10A. High Level Output Voltage vs. Temperature (I_O = 0 mA)

Figure 10B. High Level Output Voltage vs. Supply Voltage (I_O = 0 mA)



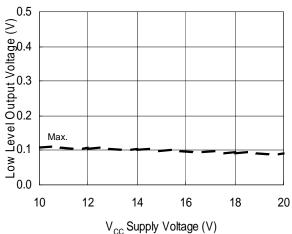
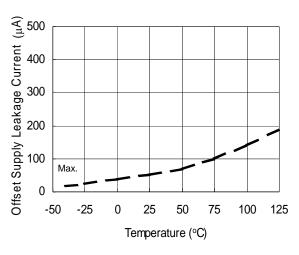


Figure 11A. Low Level Output vs.Temperature

Figure 11B. Low Level Output vs. Supply Voltage



Wax.

Max.

Max.

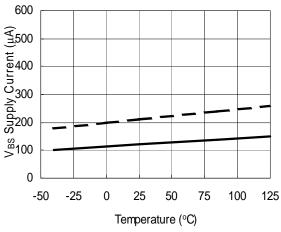
Solution 100

Max.

V_B Boost Voltage (V)

Figure 12A. Offset Supply Leakage Current vs. Temperature

Figure 12B. Offset Supply Leakage Current vs. Supply Voltage





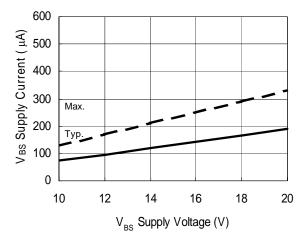
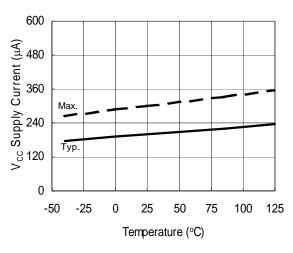


Figure 13B. V_{BS} Supply Current vs. Supply Voltage

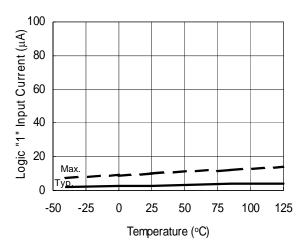


(Pi) 480 Wax. 360 No 360 No 360 No 360 Max. Typ. 0 10 12 14 16 18 20 V_{CC} Supply Voltage (V)

600

Figure 14A. V_{CC} Supply Current vs. Temperature

Figure 14B. V_{CC} Supply Current vs. Supply Voltage



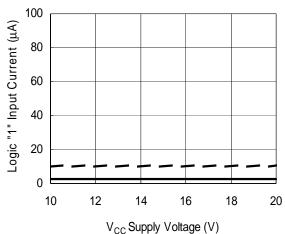


Figure 15A. Logic "1" Input Current vs. Temperature

Figure 15B. Logic "1" Input Current vs. Supply Voltage

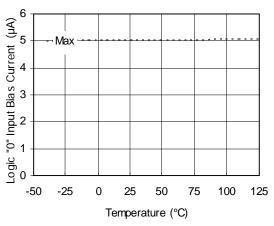


Figure 16A. Logic "0" Input Bias Current vs. Temperature

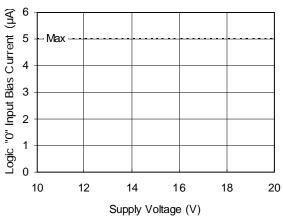
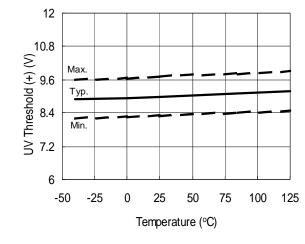


Figure 16B. Logic "0" Input Bias Current vs. Voltage



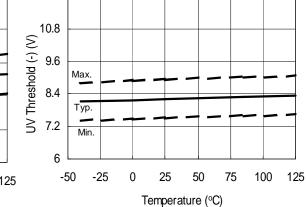
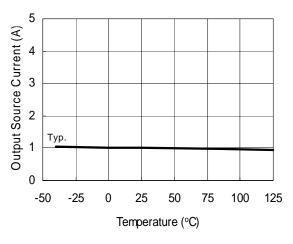


Figure 17. V_{CC} and V_{BS} Undervoltage Threshold (+) vs. Temperature

Figure 18. $\rm V_{\rm CC}$ and $\rm V_{\rm BS}$ Undervoltage Threshold (-) vs. Temperature

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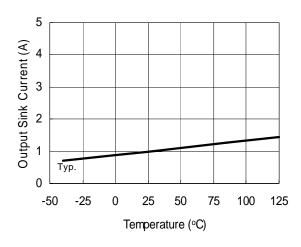
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5 (Y) the transport of the transport of

Figure 19A. Output Source Current vs. Temperature

Figure 19B. Output Source Current vs. Supply Voltage



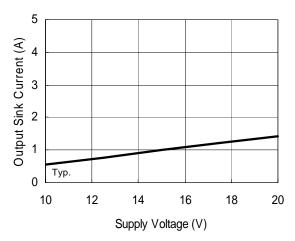


Figure 20A. Output Sink Current vs. Temperature

Figure 20B. Output Sink Current vs. Supply Voltage

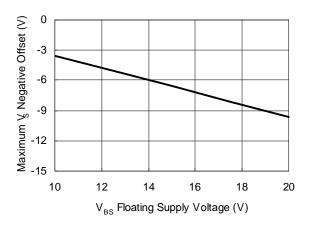


Figure 21. Maximum $\rm V_{S}$ Negative Offset vs $\rm V_{BS}$ Floating Supply Voltage

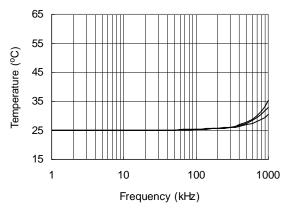


Figure 22. IRS2011S vs. Frequency (IRFBC20) $\rm R_{\rm gate} = 33~W$, $\rm V_{\rm CC} = 12~V$

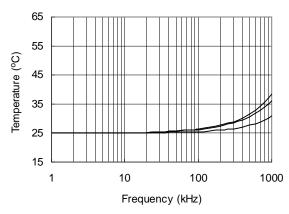
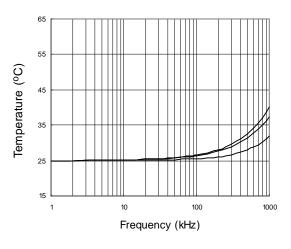


Figure 23. IRS2011S vs. Frequency (IRFBC30) $\rm R_{\rm gate} = 22~W$, $\rm V_{\rm CC} = 12~V$

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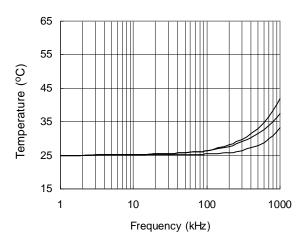


Figure 24. IRS2011S vs. Frequency (IRFBC40) $\rm R_{\rm qate} = 15~W,~V_{\rm CC} = 12~V$

Figure 25. IRS2011S vs. Frequency (IRFB23N15D) $\rm R_{\rm gate}$ =10 $\rm W$, $\rm V_{\rm CC}$ =12 V

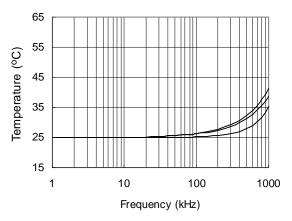
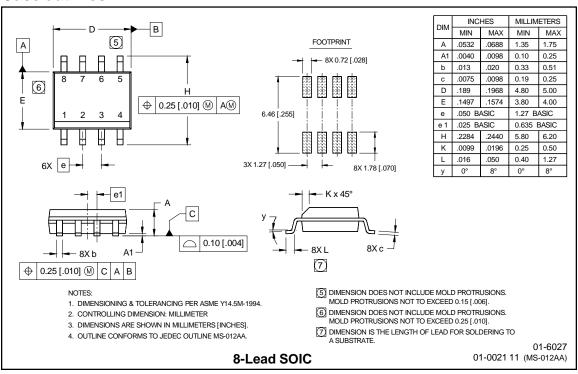
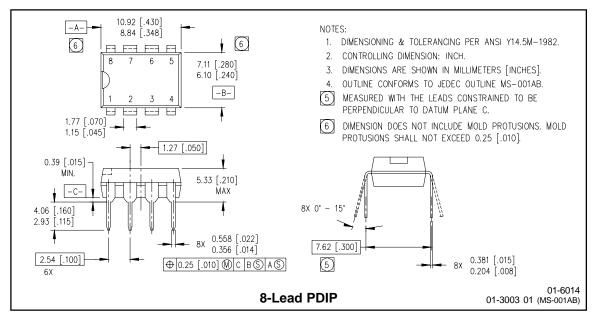


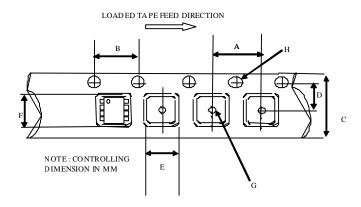
Figure 26. IRS2011S vs. Frequency (IRFB4212) $\rm R_{\rm gate} = 10~W,~V_{\rm CC} = 12~V$

Case outlines



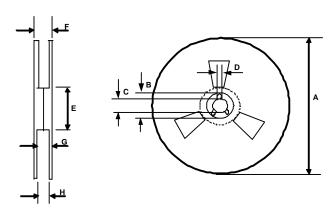


Tape & Reel 8-lead SOIC



CARRIER	TAPE DIMENSION	FΟ	R 8SOICN
	M etric		Im p

	Ме	M etric		erial
Code	Min	Max	Min	Max
Α	7.90	8.10	0.311	0.318
В	3.90	4.10	0.153	0.161
С	11.70	12.30	0.46	0.484
D	5.45	5.55	0.214	0.218
E	6.30	6.50	0.248	0.255
F	5.10	5.30	0.200	0.208
G	1.50	n/a	0.059	n/a
Н	1.50	1.60	0.059	0.062

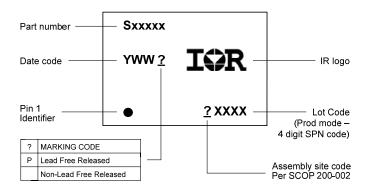


REEL DIMENSIONS FOR 8SOICN

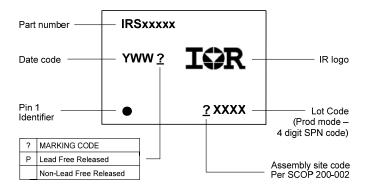
	M etric		Im p	erial
Code	Min	Max	Min	Max
Α	329.60	330.25	12.976	13.001
В	20.95	21.45	0.824	0.844
С	12.80	13.20	0.503	0.519
D	1.95	2.45	0.767	0.096
E	98.00	102.00	3.858	4.015
F	n/a	18.40	n/a	0.724
G	14.50	17.10	0.570	0.673
H	12.40	14.40	0.488	0.566

LEADFREE PART MARKING INFORMATION

SOIC



PDIP



ORDER INFORMATION

8-Lead PDIP IRS2011PbF 8-Lead SOIC IRS2011SPbf 8-Lead SOIC Tape & Reel IRS2011STRPbF



SOIC-8 package is MSL2 qualified. and qualified for the industrial level.

This product has been designed and qualified for the industrial level.

Qualification standards can be found on IR's website http://www.irf.com/

WORLD HEADQUARTERS: 233 Kansas Street, El Segundo, California 90245 Tel: (310)252-7105

Data and specifications subject to change without notice. 9/7/2010